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WHAT WE CLAIM IS:

1. A write/read head supporting mechanism comprising a slider provided with an electromagnetic transducer element or an optical module, and a suspension, wherein said slider is supported on said suspension by way of an actuator for displacing said slider, an electrical connection to said electromagnetic transducer element or said optical module is made by a first interconnecting arrangement movable and/or deformable in a displacement direction of said slider by said actuator, and an electrical connection to said actuator is made by a second interconnecting arrangement.

2. The write/read head supporting mechanism according to claim 1, wherein said first interconnecting arrangement includes a lead wire floating away from a surface of said suspension.

3. The write/read head supporting mechanism according to claim 2, wherein said lead wire floating away form the surface of said suspension is a bonding wire.

4. The write/read head supporting mechanism according to claim 1, wherein said first interconnecting arrangement includes a flexible printed wire.

5. The write/read head supporting mechanism according to claim 1, wherein said first interconnecting arrangement is formed by bringing wires in close contact with a surface of said suspension, and then removing a part of said suspension so that a part of said wires in close contact with the surface of said suspension is placed in a floating state.

6. The write/read head supporting mechanism according to claim 1, wherein said first interconnecting arrangement is formed on a surface of said suspension while said first interconnecting arrangement is in close contact therewith, and allowing an area of low rigidity to exist at a part of said suspension, so that said first interconnecting arrangement is movable and/or deformable in the displacement direction of said slider by said actuator.

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7. The write/read head supporting mechanism according to any one of claims 1 to 6, wherein at least one part of said first interconnecting arrangement and at least one part of said second interconnecting arrangement are unable to exist on the same surface of said suspension.

8. The write/read head supporting mechanism according to any one of claims 1 to 7, wherein said actuator makes use of an inverse piezoelectric effect or an electrostrictive effect.

9. The write/read head supporting mechanism according to any one of claims 1 to 8, wherein a head driving IC chip is built on said suspension.

10. The write/read head supporting mechanism according to any one of claims 1 to 9, which includes a main actuator for driving said suspension.

11. A write/read system which comprises a write/read head supporting mechanism as recited in any one of claims 1 to 10.